



# Conductive Paste

## for Crystalline Silicon Solar Cell

### ● C-9200 Series Aluminum Paste

C-9200 series is a kind of environmental protective Aluminum composition designed on silicon solar cell back side electrode. It is perfectly compatible with silicon wafer thermal expansion. It bears excellent printing, pure color, delicate surface, good adhesion, low bending and high efficiency, etc.

### ● C-9300 Series Back Side Silver Paste

C-9300 series is a highly conductive silver composition designed on silicon solar cell back side electrode, Lead and cadmium free. It's developed to provide excellent adhesion when used in conjunction with backside aluminum compositions. The conductive component in silver shallow emitter paste will be the excellent ohmic contact characteristics with silicon chip when co-fired. It has the features of good printing, low contact resistance, good solderability and weldability.

### ● C-9600 Series Front Side Silver Paste

C-9600 series is a highly conductive solderable and cadmium free silver composition designed on silicon solar cell front side electrode. The conductive component will be the excellent ohmic contact characteristics with silicon chip penetrating SiNx film, with good printing, lower contact resistance, excellent fine line capabilities,

	C-9201	C-9202	C-9203	C-9301	C-9302	C-9601	C-9602
Solid Content (%)	70~80			60-65	55-60	88-90	90-92
Viscosity (Pa.S)	40~60			100 +/-20		260-320	320-400
Fineness	<=15µm			<=10µm			
Printing screen	200~300 mesh			250-300 mesh		280-400 mesh	
Drying	Infrared drying furnace, 180~240°C /2~4min; Circulated air drying, 220°C /8~10min			Infrared drying furnace ; 180~240°C /2~4min, Vertical drying oven 250~300°C/3min,		Infrared drying furnace 180~240°C/1~3min,; Vertical drying oven 250~300°C/3min,	
Peak firing temp.	750~850°C /1~5 seconds						
Firing thickness	--			15 +/-2µm		26 +/-2µm	
EVA Stripping Strength	Without any breaking off						
Adhesion	--			>=5.5N	>=4.5N	>=5.0N	>=5.5N
Boiling Test	Without any frothiness and breaking off						
Cell plate bending(mm)	<= 1.1	<=1.15	<=1	--			
Resistivity( mΩ/□) (after fired)	<= 30			3	4	2	1.8
Solderability	>95%, (260°C , 62Sn/36Pb/2Ag)						
Weldability (Second)				15	10	10	15
	( 200°C , 62Sn/36Pb/2Ag )						
Cell Efficiency	Mono crystalline silicon, ≥ 18.2%; Polycrystalline silicon, ≥ 16.8%;						
Thinner	V-100			V-200		V-300	

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